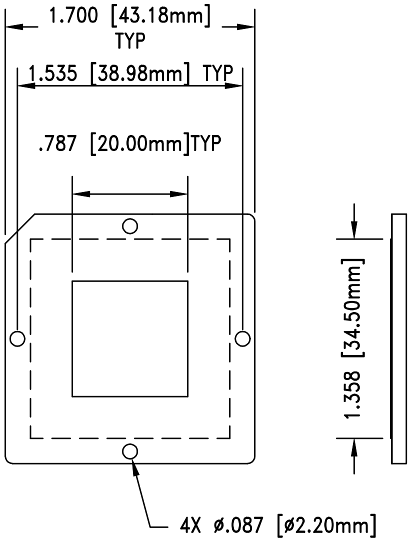
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	4/27/00	M.D.
B	UPDATED PAD LAYOUT AND DIMS	03/30/01	H.N.
C	UPDATED DRAWING	10/10/01	H.N.

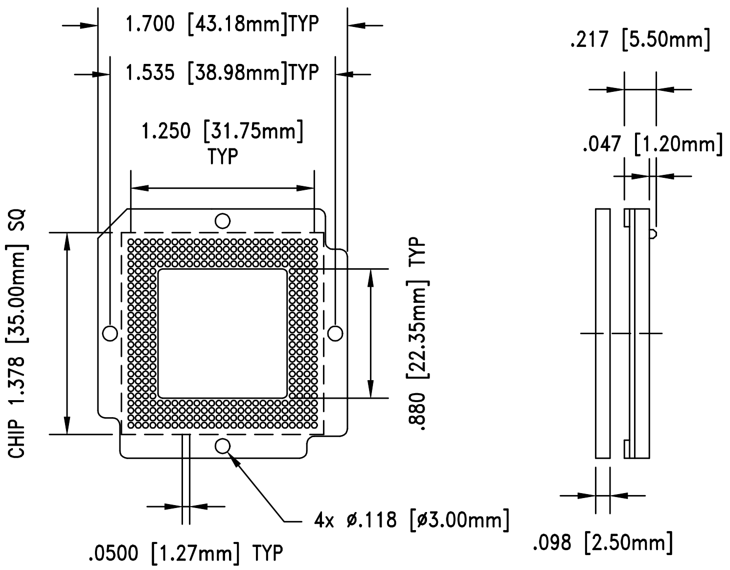
SKT772

DOD 4772

SOCKET



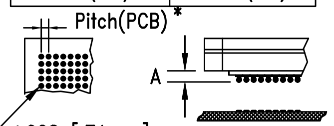
RETENTION FRAME



FOR LOW PROFILE CHIP =<1.00mm THICKNESS W/O SOLDERBALL

RECOMMENDED PAD LAYOUT

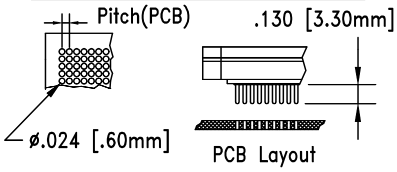
SOLDERTAIL STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = (-SM) YY = (-30)	XX = (-RC) YY = (-29)



30= standard SMD ("A" = .047 [1.20mm])
29= raised SMD ("A" = .197 [5.00mm])

BALL DIAMETER FOR:
-29(RC) = .026 [0.66mm]
-30(SM) = .026 [0.66mm]

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET) YY = (-70)



PIN DIAMETER FOR:
-70(ET) = .018 [0.45mm]

* The pitch dimension depends on your Ball Grid Array Package

PACKAGE SPECIFICATIONS	
PIN COUNT	= 352
LEAD PITCH	= 1.27mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 35.00mm

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED

Emulation Technology, Inc.
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2344 Walsh Avenue, Bldg. F
Santa Clara, Ca 95051
TEL:(408)982-0660
FAX:(408)982-0664

SHEET: 1 OF 1
DATE: 10/10/01
REVISION: C

ASSEMBLY DRAWING

CHECKED: Perry Munroe
DRAWN: MIGUEL DELGADILLO
ITEM: S-BGA-26-352-XX

DO NOT SCALE DRAWING

DESCRIPTION: BPW-352-2BG026-YY